

# PIC18F2455/2550/4455/4550

## 28.2 DC Characteristics: Power-Down and Supply Current

### PIC18F2455/2550/4455/4550 (Industrial)

### PIC18LF2455/2550/4455/4550 (Industrial) (Continued)

PIC18LF2455/2550/4455/4550 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature      -40°C ≤ TA ≤ +85°C for industrial					
PIC18F2455/2550/4455/4550 (Industrial)			Standard Operating Conditions (unless otherwise stated) Operating temperature      -40°C ≤ TA ≤ +85°C for industrial					
Param No.	Symbol	Device	Typ	Max	Units	Conditions		
		Supply Current (IDD) <sup>(2)</sup>						
		PIC18LFX455/X550	250	500	μA	-40°C	VDD = 2.0V	FOSC = 1 MHz ( <b>PRI_RUN</b> , EC oscillator)
			250	500	μA	+25°C		
			250	500	μA	+85°C		
		PIC18LFX455/X550	550	650	μA	-40°C	VDD = 3.0V	
			480	650	μA	+25°C		
			460	650	μA	+85°C		
		All devices	1.2	1.6	mA	-40°C	VDD = 5.0V	
			1.1	1.5	mA	+25°C		
			1.0	1.4	mA	+85°C		
		PIC18LFX455/X550	0.74	2.0	mA	-40°C	VDD = 2.0V	FOSC = 4 MHz ( <b>PRI_RUN</b> , EC oscillator)
			0.74	2.0	mA	+25°C		
			0.74	2.0	mA	+85°C		
		PIC18LFX455/X550	1.3	3.0	mA	-40°C	VDD = 3.0V	
			1.3	3.0	mA	+25°C		
			1.3	3.0	mA	+85°C		
		All devices	2.7	6.0	mA	-40°C	VDD = 5.0V	
			2.6	6.0	mA	+25°C		
			2.5	6.0	mA	+85°C		
		All devices	15	35	mA	-40°C	VDD = 4.2V	FOSC = 40 MHz ( <b>PRI_RUN</b> , EC oscillator)
			16	35	mA	+25°C		
			16	35	mA	+85°C		
		All devices	21	40	mA	-40°C	VDD = 5.0V	
			21	40	mA	+25°C		
			21	40	mA	+85°C		
		All devices	20	40	mA	-40°C	VDD = 4.2V	FOSC = 48 MHz ( <b>PRI_RUN</b> , EC oscillator)
			20	40	mA	+25°C		
			20	40	mA	+85°C		
		All devices	25	50	mA	-40°C	VDD = 5.0V	
			25	50	mA	+25°C		
25	50		mA	+85°C				

**Legend:** Shading of rows is to assist in readability of the table.

**Note 1:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

**2:** The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;

MCLR = VDD; WDT enabled/disabled as specified.

**3:** Standard low-cost 32 kHz crystals have an operating temperature range of -10°C to +70°C. Extended temperature crystals are available at a much higher cost.

**4:** BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

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Param No.	Symbol	Device	Typ	Max	Units	Conditions		
		Supply Current ( $I_{DD}$ ) <sup>(2)</sup>						
		PIC18LFX455/X550	65	130	$\mu\text{A}$	$-40^{\circ}\text{C}$	$V_{DD} = 2.0\text{V}$	FOSC = 1 MHz ( <b>PRI_IDLE</b> mode, EC oscillator)
			65	120	$\mu\text{A}$	$+25^{\circ}\text{C}$		
			70	115	$\mu\text{A}$	$+85^{\circ}\text{C}$		
		PIC18LFX455/X550	120	270	$\mu\text{A}$	$-40^{\circ}\text{C}$	$V_{DD} = 3.0\text{V}$	
			120	250	$\mu\text{A}$	$+25^{\circ}\text{C}$		
			130	240	$\mu\text{A}$	$+85^{\circ}\text{C}$		
		All devices	230	480	$\mu\text{A}$	$-40^{\circ}\text{C}$	$V_{DD} = 5.0\text{V}$	
			240	450	$\mu\text{A}$	$+25^{\circ}\text{C}$		
			250	430	$\mu\text{A}$	$+85^{\circ}\text{C}$		
		PIC18LFX455/X550	255	475	$\mu\text{A}$	$-40^{\circ}\text{C}$	$V_{DD} = 2.0\text{V}$	FOSC = 4 MHz ( <b>PRI_IDLE</b> mode, EC oscillator)
			260	450	$\mu\text{A}$	$+25^{\circ}\text{C}$		
			270	430	$\mu\text{A}$	$+85^{\circ}\text{C}$		
		PIC18LFX455/X550	420	900	$\mu\text{A}$	$-40^{\circ}\text{C}$	$V_{DD} = 3.0\text{V}$	
			430	850	$\mu\text{A}$	$+25^{\circ}\text{C}$		
			450	810	$\mu\text{A}$	$+85^{\circ}\text{C}$		
		All devices	0.9	1.5	$\text{mA}$	$-40^{\circ}\text{C}$	$V_{DD} = 5.0\text{V}$	
			0.9	1.4	$\text{mA}$	$+25^{\circ}\text{C}$		
			0.9	1.3	$\text{mA}$	$+85^{\circ}\text{C}$		
		All devices	6.0	16	$\text{mA}$	$-40^{\circ}\text{C}$	$V_{DD} = 4.2\text{V}$	FOSC = 40 MHz ( <b>PRI_IDLE</b> mode, EC oscillator)
			6.2	16	$\text{mA}$	$+25^{\circ}\text{C}$		
			6.6	16	$\text{mA}$	$+85^{\circ}\text{C}$		
		All devices	8.1	18	$\text{mA}$	$-40^{\circ}\text{C}$	$V_{DD} = 5.0\text{V}$	
			8.3	18	$\text{mA}$	$+25^{\circ}\text{C}$		
			9.0	18	$\text{mA}$	$+85^{\circ}\text{C}$		
		All devices	8.0	18	$\text{mA}$	$-40^{\circ}\text{C}$	$V_{DD} = 4.2\text{V}$	FOSC = 48 MHz ( <b>PRI_IDLE</b> mode, EC oscillator)
			8.1	18	$\text{mA}$	$+25^{\circ}\text{C}$		
			8.2	18	$\text{mA}$	$+85^{\circ}\text{C}$		
		All devices	9.8	21	$\text{mA}$	$-40^{\circ}\text{C}$	$V_{DD} = 5.0\text{V}$	
			10.0	21	$\text{mA}$	$+25^{\circ}\text{C}$		
			10.5	21	$\text{mA}$	$+85^{\circ}\text{C}$		

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- 2:** The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.  
The test conditions for all  $I_{DD}$  measurements in active operation mode are:  
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